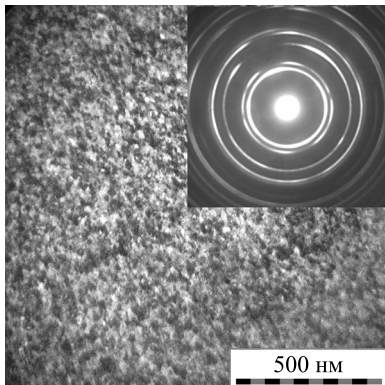
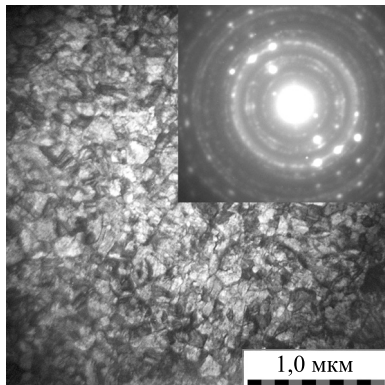
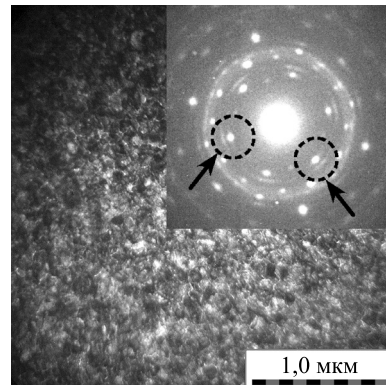
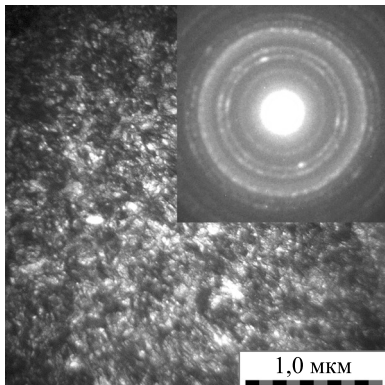
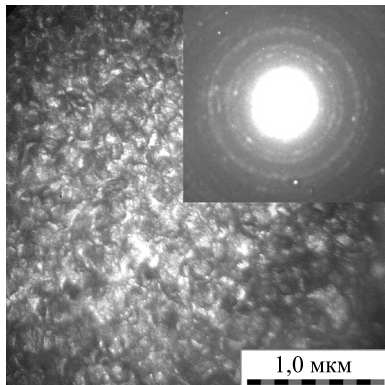
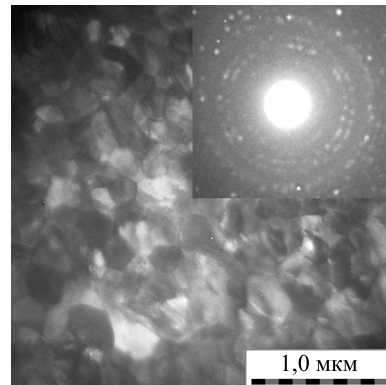


*a/a**б/б**в/в**г/г**д/д**е/е*

*Рис. 1.* Светлопольные Р-ПЭМ-микрофотографии и ПЭД-картины (на вставках), полученные от структуры Ni – V/Pt/Si с толщиной слоя сплава Ni – V 40 нм до БТО (*а*) и после БТО при температуре 400 °С (*б*), 450 °С (*в*), 500 °С (*г*) и 600 °С (*е*)

*Fig. 1.* Bright-field plan-view transmission electron microscopy micrographs and transmission electron diffraction patterns (on insets) obtained from the Ni – V/Pt/Si structure with a Ni – V alloy layer thickness of 40 nm before rapid heat treatment (*a*) and after rapid heat treatment at a temperature of 400 °C (*b*), 450 °C (*c*), 500 °C (*d*), 550 °C (*e*) and 600 °C (*f*)